



2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

PowerDI[®]123

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- High Current Capability and Low Forward Voltage Drop
- Lead Free Finish, RoHS Compliant (Note 1)
- "Green" Molding Compound (No Br, Sb)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: PowerDI[®]123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-02
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.01 grams (approximate)



Top View

Ordering Information (Note 2)

Part Number	Case	Packaging
DFLS230L-7	PowerDI [®] 123	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
- 2. For packaging details, go to our website at http://www.diodes.com.

Marking Information



F03A = Product Type Marking Code YM = Date Code Marking Y = Year (ex: T = 2006) M = Month (ex: 9 = September)

Date Code Key

Year	2004	20	005	2006	2007	20	80	2009	2010	20	11	2012
Code	R		S	T	U	'	V	W	Х	,	Y	Z
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Average Forward Current @ T _T = 121°C	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	33	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _D	1.67	W
Power Dissipation (Note 4)	P _D	556	mW
Thermal Resistance Junction to Ambient (Note 3)	$R_{ hetaJA}$	60	°C/W
Thermal Resistance Junction to Ambient (Note 4)	$R_{ heta JA}$	180	°C/W
Thermal Resistance Junction to Soldering (Note 5)	$R_{ heta JS}$	10	°C/W
Operating Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C

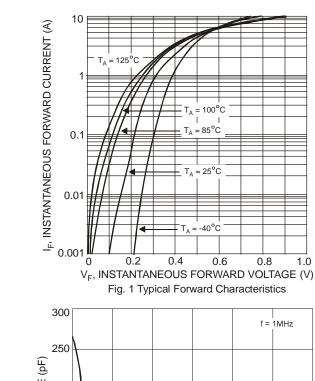
Electrical Characteristics @T_A = 25°C unless otherwise specified

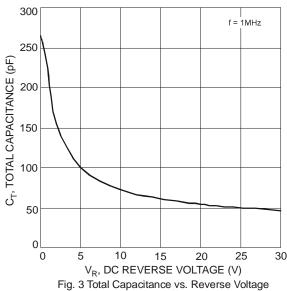
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	30		_	V	$I_R = 1.0 \text{mA}$
Forward Voltage	VF	_	0.310	_	· · · /	I _F = 1.0A
r olward voltage		_	0.375	0.420		$I_F = 2.0A$
Leakage Current (Note 6)	I _R	_	0.260	_	mA	$V_R = 5V, T_A = 25^{\circ}C$ $V_R = 30V, T_A = 25^{\circ}C$
Leakage Current (Note 6)		_		1.0		$V_R = 30V, T_A = 25^{\circ}C$
Total Capacitance	C _T	_	76	_	pF	$V_R = 10V, f = 1.0MHz$

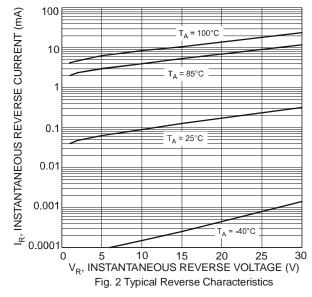
Notes:

- 3. Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode. $T_A = 25$ °C.
- 4. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com.
- 5. Theoretical R_{0JS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
- 6. Short duration pulse test used to minimize self-heating effect.









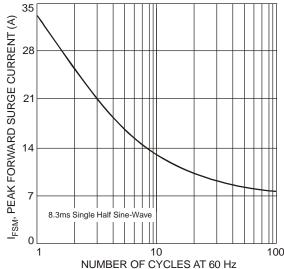
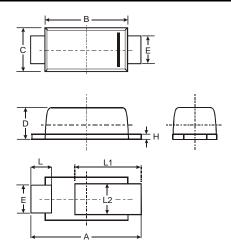


Fig. 4 Maximum Non-Repetitive Peak Forward Surge Current

Package Outline Dimensions

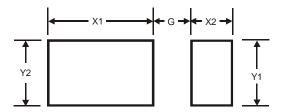


PowerDI°123							
Dim	Min	Max	Тур				
Α	3.50	3.90	3.70				
В	2.60	3.00	2.80				
O	1.63	1.93	1.78				
ם	0.93	1.00	0.98				
Е	0.85	1.25	1.00				
Н	0.15	0.25	0.20				
L	0.55	0.75	0.65				
L1	1.80	2.20	2.00				
L2	0.95	1.25	1.10				
All Dimensions in mm							

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Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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